

Material Features:

- Low Density
- Low thermal resistance
- Good thermal stability

Applications

- Graphic Processors
- Base stations
- Microprocessors
- Data Centers

Storage Conditions:

- Store in dark environment
- Storage Temperature: $\leq 30^{\circ}\text{C}$
- Storage Humidity: $\leq 70\%$

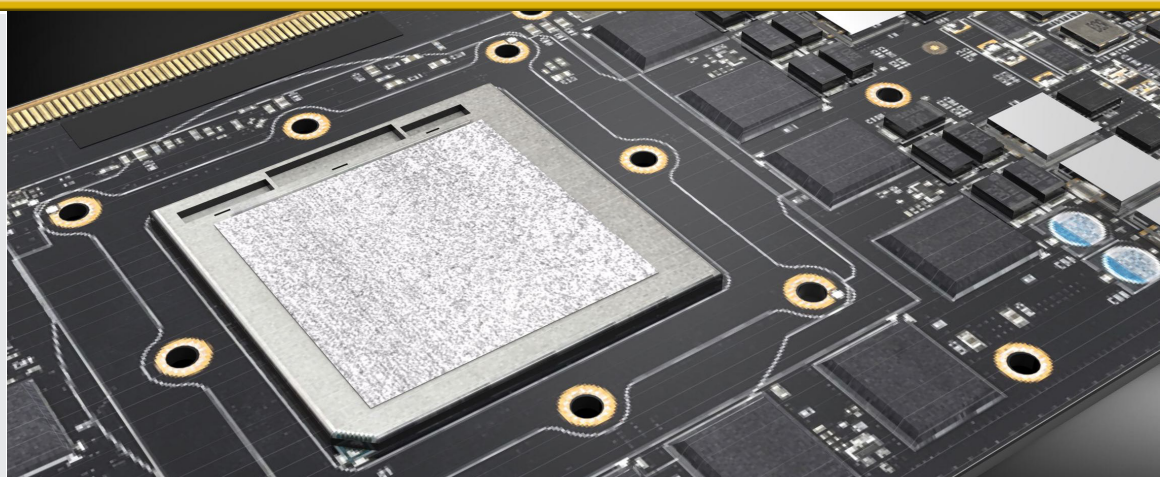
Shelf Life:

- Stored at storage conditions:
Two years

Short Term Operating Temperature:

- 500°F (260°C) for 30 minutes.

STATEMENT OF LIEU OF WARRANTY: All technical information and data in this document is based on tests and is believed to be accurate and reliable. Nevertheless, since the products described herein are not provided to conform with mutually accepted specifications and the use thereof is unknown, the manufacturer and seller of the products do not guarantee results, freedom from patent infringement, or suitability of the products for any application thereof. The manufacturer and seller of the products described in this document will provide all possible technical assistance and will replace any products proven defective. No statement or recommendations made by the manufacturer or seller not contained herein shall have any force of effect unless in conformity with an agreement signed by an officer of the seller and manufacturer. Product testing by the purchaser is recommended in order to confirm expected results.



TGN Series

Leader Tech's TGN series are a new ultra-thin thermal pad with low thermal resistance. This thermal pad is fabricated by combining graphene and silicone. The materials are arranged in the polymer matrix in an orderly manner to form a good thermally conductive path, which greatly improves the efficiency of heat conduction. In addition, this material has high resiliency and low density which can be used as a replacement of thermal grease material.

Part Series	Test Method	TGN700	TGN900	TGN1300
Thermal Properties				
Thermal Conductivity Z axis (W/m-K)	ASTM D 5470	70	90	130
Thermal Conductivity X axis (W/m-K)	ASTM D 5470	600	600	600
Thermal Conductivity Y axis (W/m-K)	ASTM D 5470	25	25	25
Thermal Impedance ($^{\circ}\text{C-in}^2/\text{W}$; @50psi)	ASTM D 5470	≤ 0.090	≤ 0.070	≤ 0.050
Physical Properties				
Color	Visual	Black	Black	Black
Thickness Range (in, (mm))	ASTM D 374	0.008-0.031 (0.2-0.8)	0.008-0.031 (0.2-0.8)	0.008-0.020 (0.2-0.5)
Width & Length (in, (mm))	N/A	3.54 x 3.54 (90 x 90)	3.54 x 3.54 (90 x 90)	1.57 x 1.57 (40 x 40)
Density (lb/in ³ , (g/cc))	ASTM D 792	0.022 (0.6)	0.022 (0.6)	0.036 (1)
Compression Ratio @50 psi (%)	ASTM C 165	≥ 50	≥ 50	≥ 25
Compression Stress @50% (psi)	ASTM D 575	≤ 60	≤ 60	≤ 150
Tensile Strength (M Pa)	ASTM D 412	≥ 0.05 X axis ≥ 0.02 Y axis	≥ 0.05 X axis ≥ 0.02 Y axis	≥ 0.05
Resilience (%)	ASTM D 575	≥ 60	≥ 60	≥ 70
Operating Temperature($^{\circ}\text{F}$ (C))	IEC60068-2-14	-40 to 302 (-40 to 150)	-40 to 302 (-40 to 150)	-40 to 302 (-40 to 150)
Shelf Life (Months)	N/A	24	24	24

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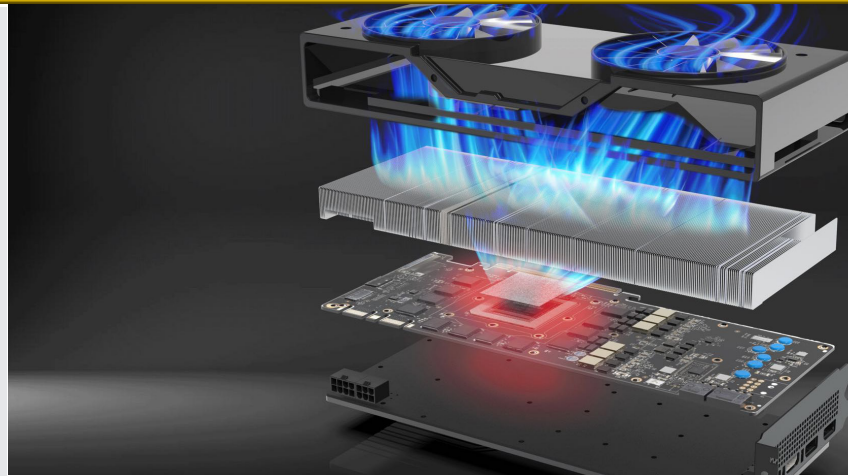
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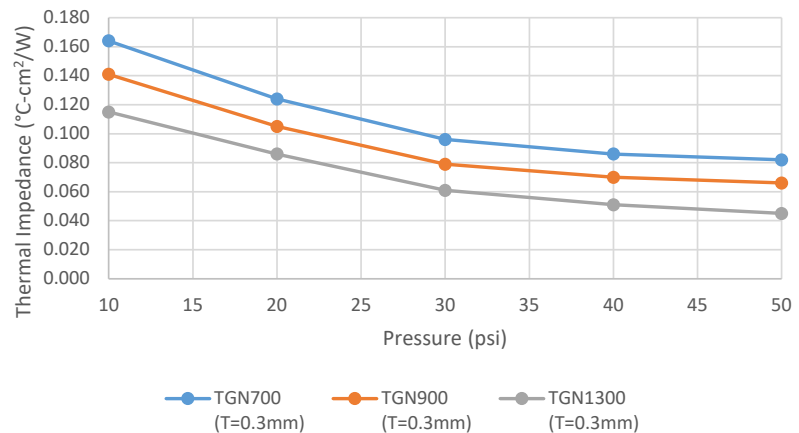
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Thermal Impedance



Compression Ratio

